



Effects of X-ray and γ -ray Irradiation on 2D and 3D CMOS SPADs

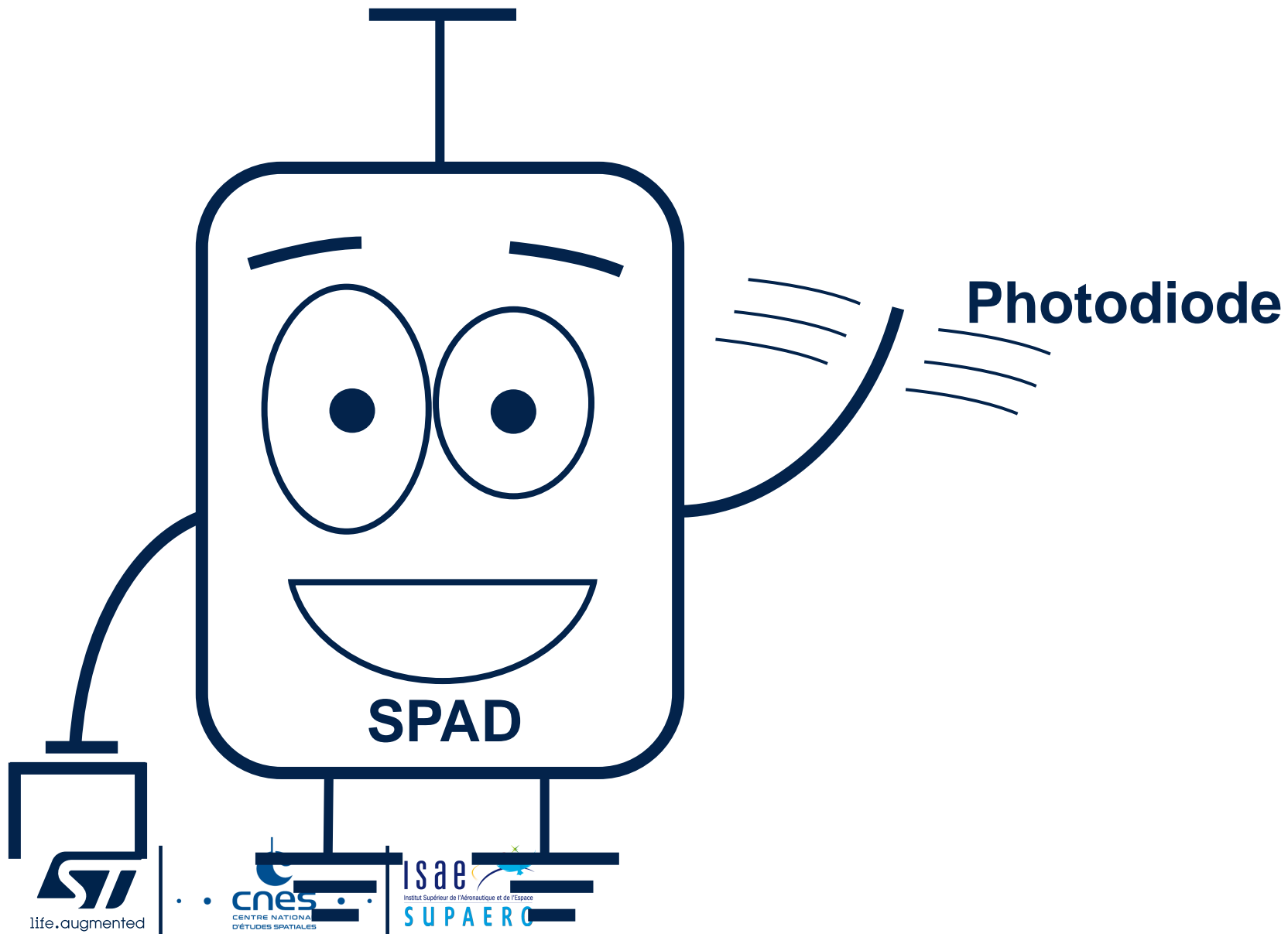
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¹CNES

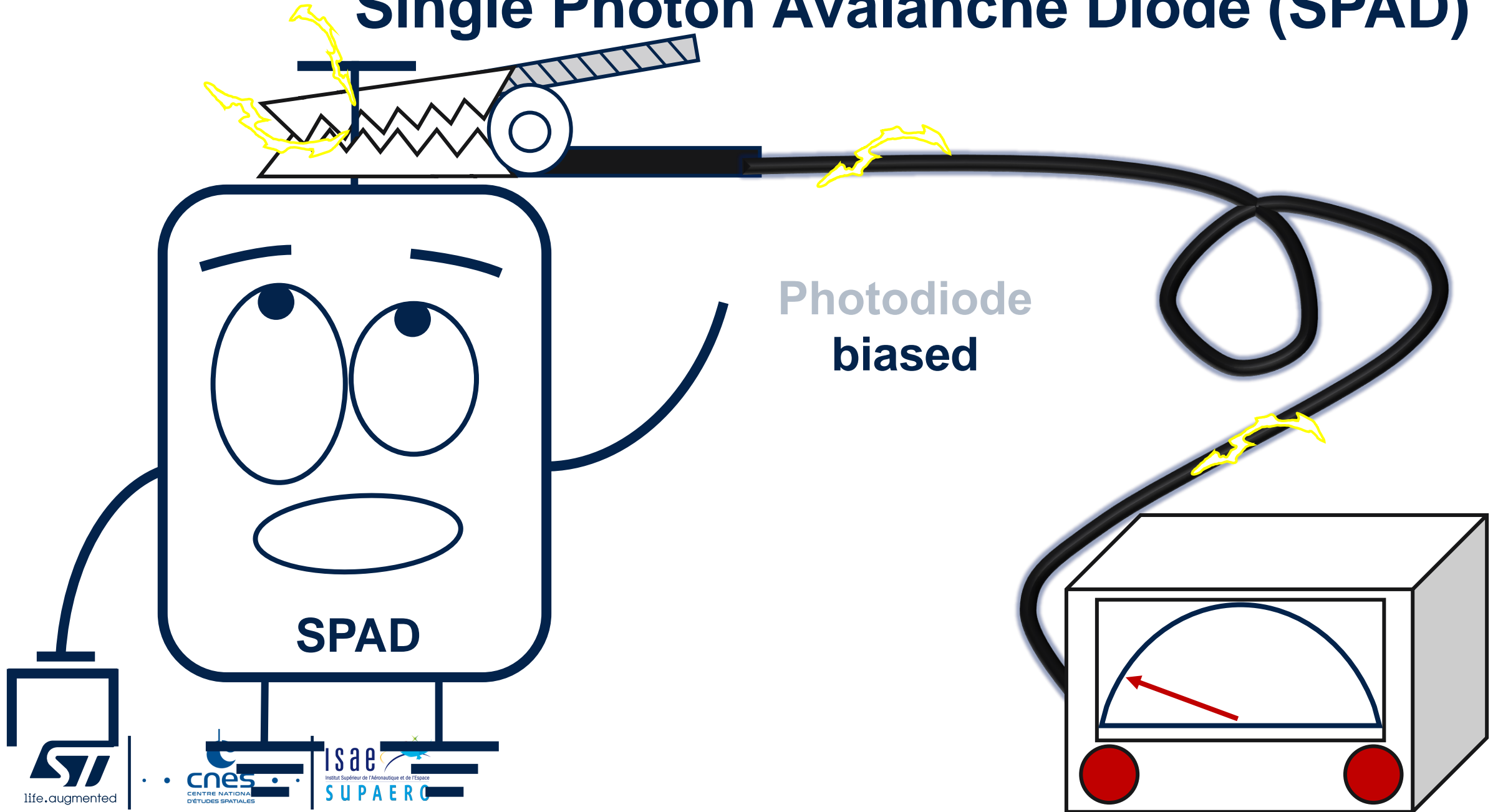
²STMicroelectronics

³ISAE-SUPAERO

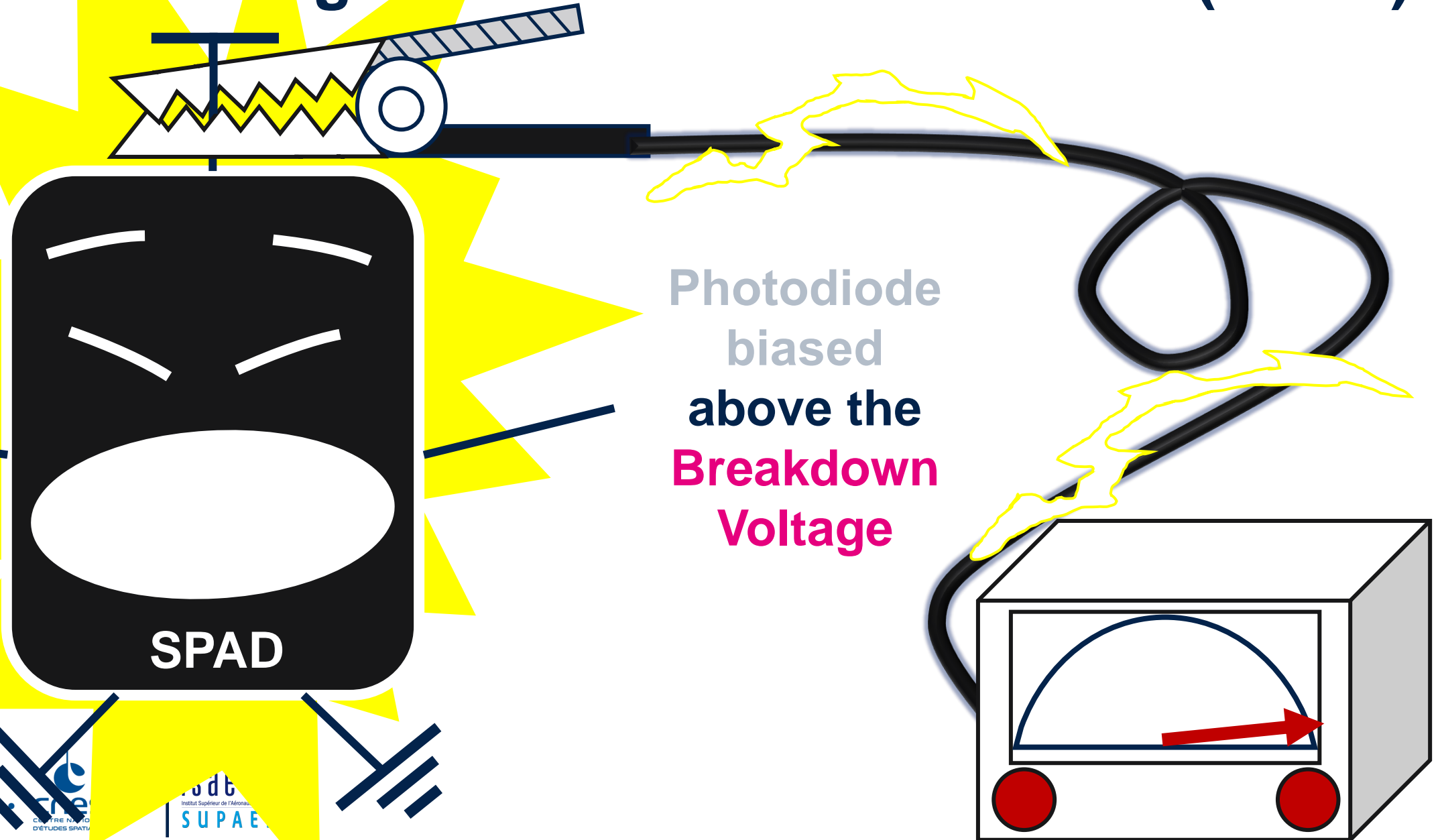
Single Photon Avalanche Diode (SPAD) ?



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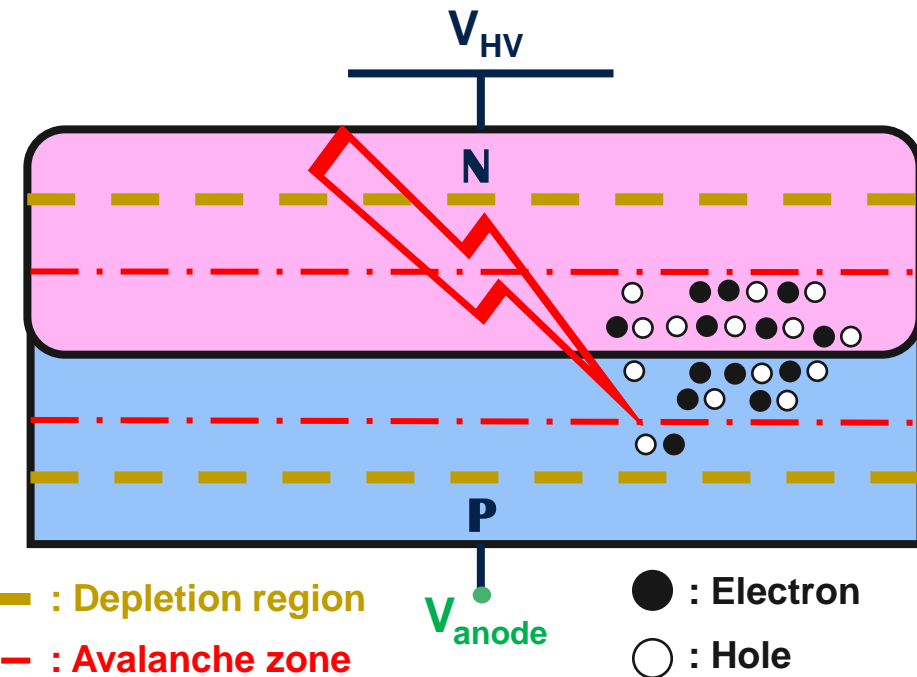
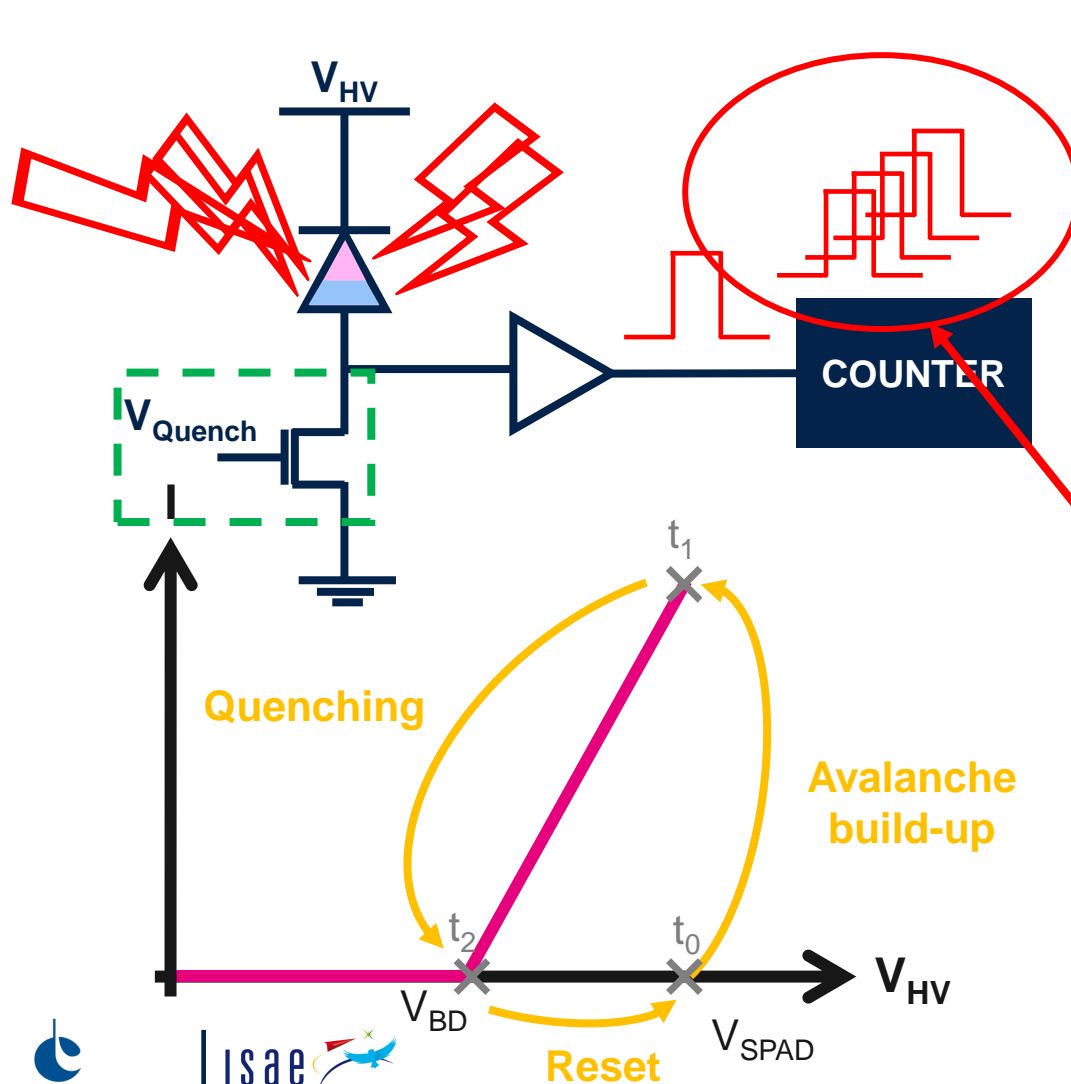
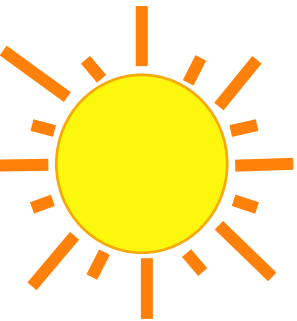


Single Photon Avalanche Diode (SPAD) ?



Single Photon Avalanche Diodes (SPADs)?

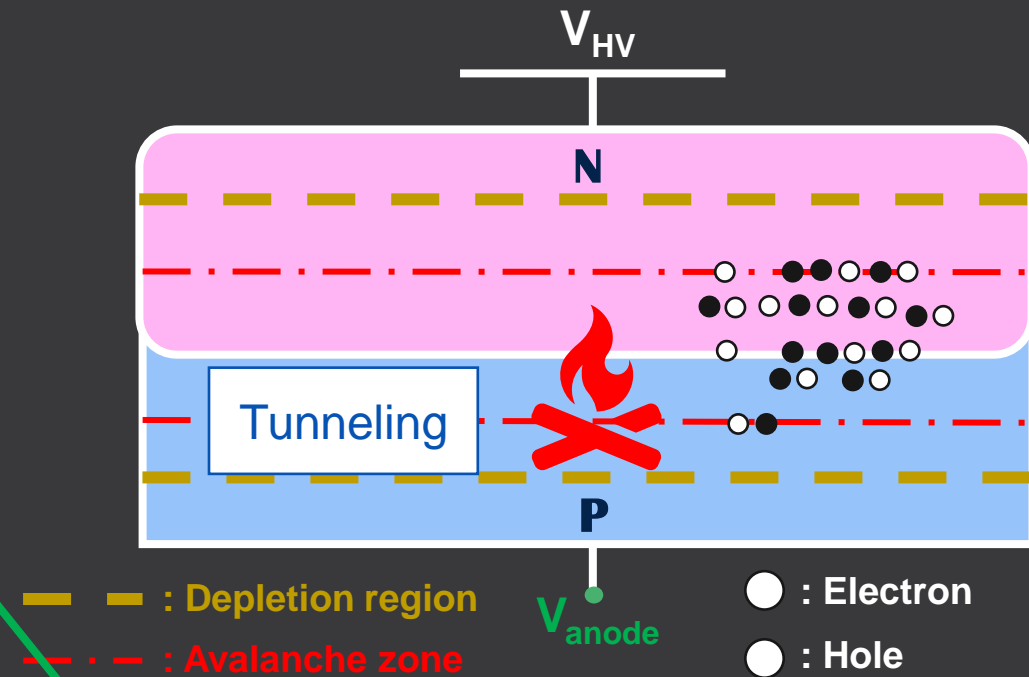
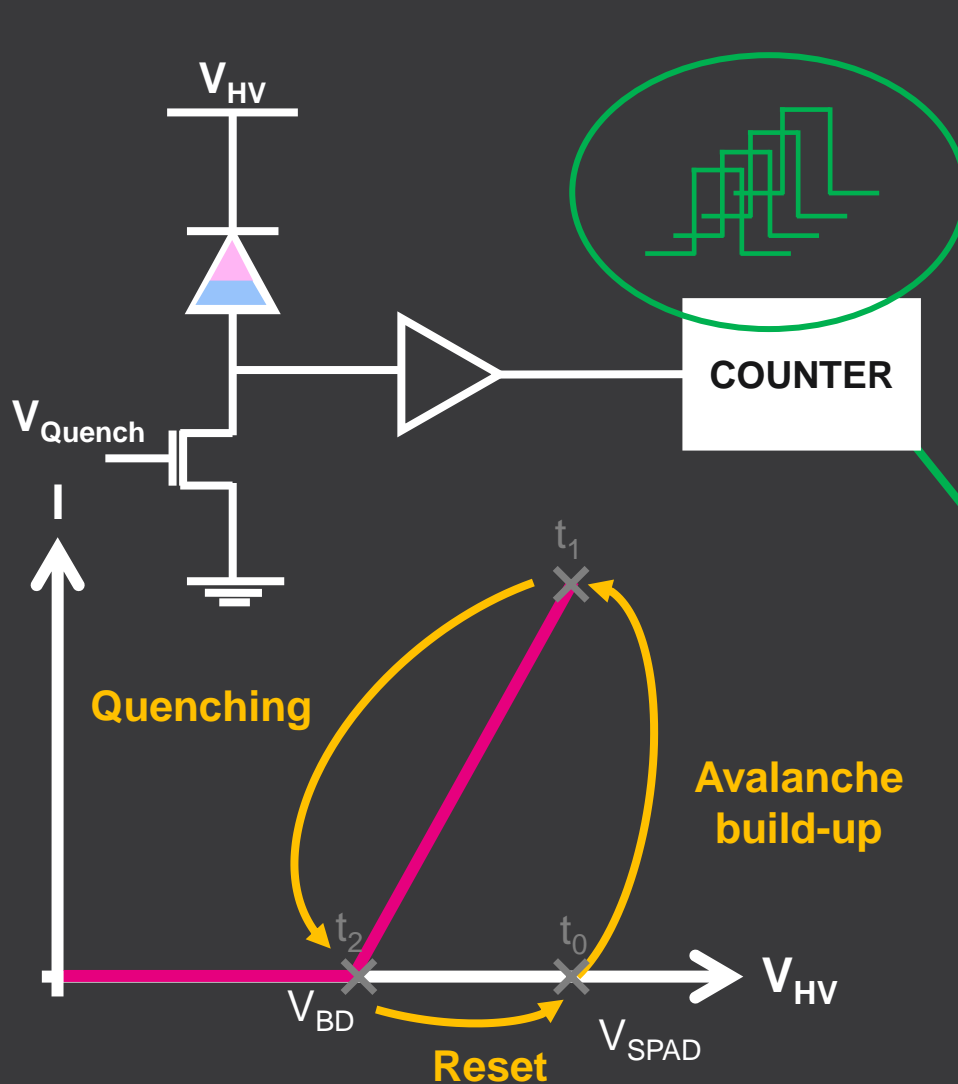
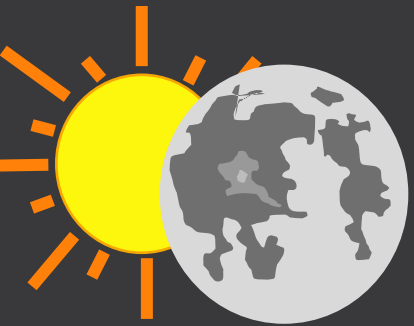
Photodiodes biased **above breakdown**:



Counts per second (cps)

Single Photon Avalanche Diodes (SPADs)?

- Photodiodes biased **above breakdown**:



Dark Count Rate (DCR)

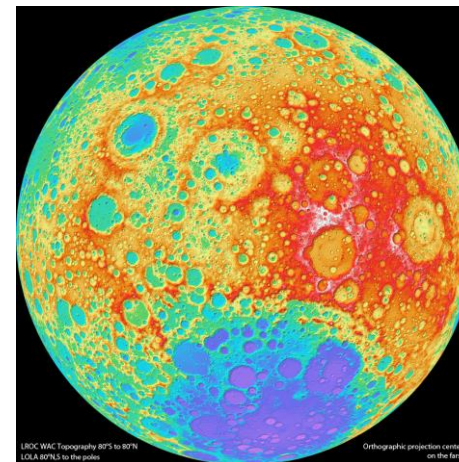
Use of SPADs in Space

SPADs → Low light sensitivity + high timing performances (hundreds of ps)

- Time of Flight
 - Space Rendezvous
 - Earth observation (LIDAR)
 - Altimetry/Topography
- 3D-Imaging



Space Rendezvous



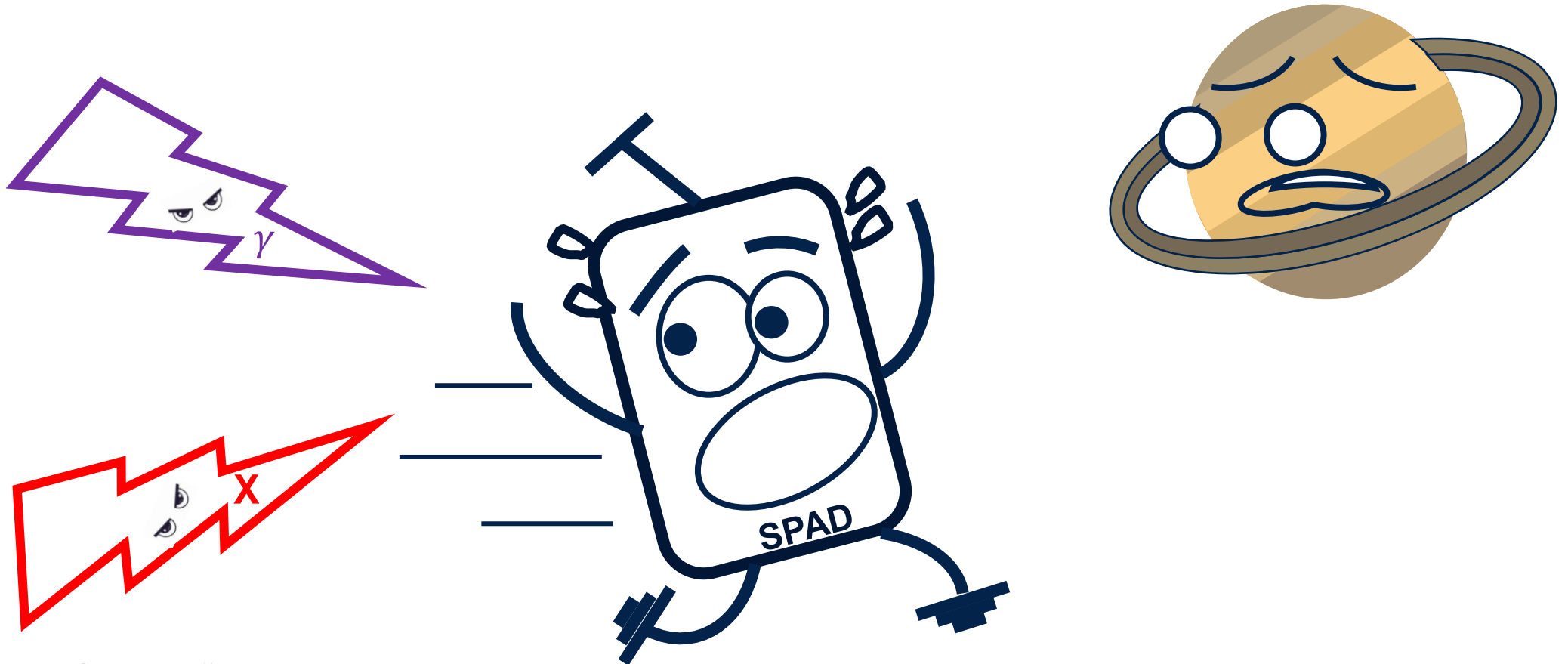
Lunar topography (LOLA instrument, credits: NASA GSFC)



LiDAR

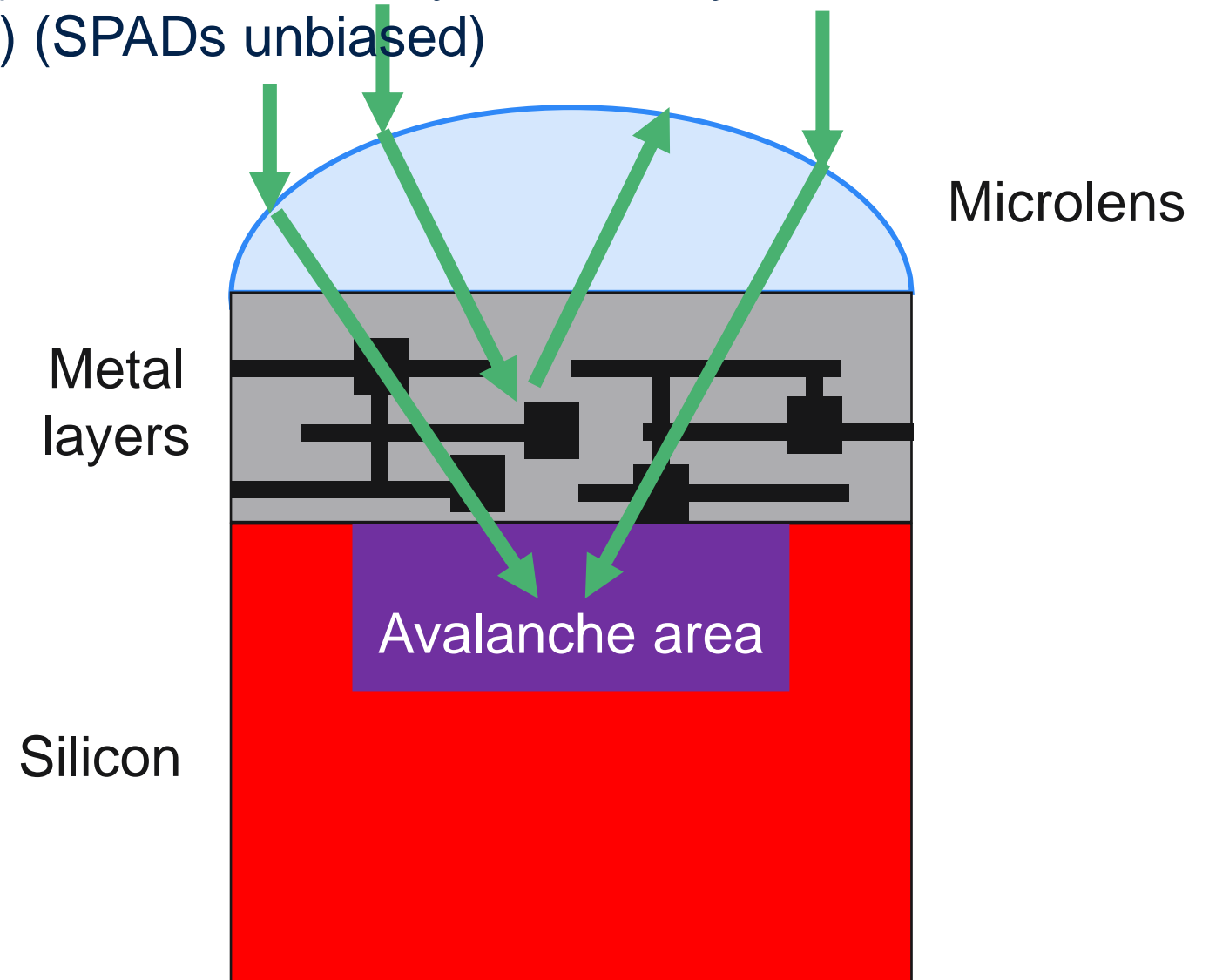
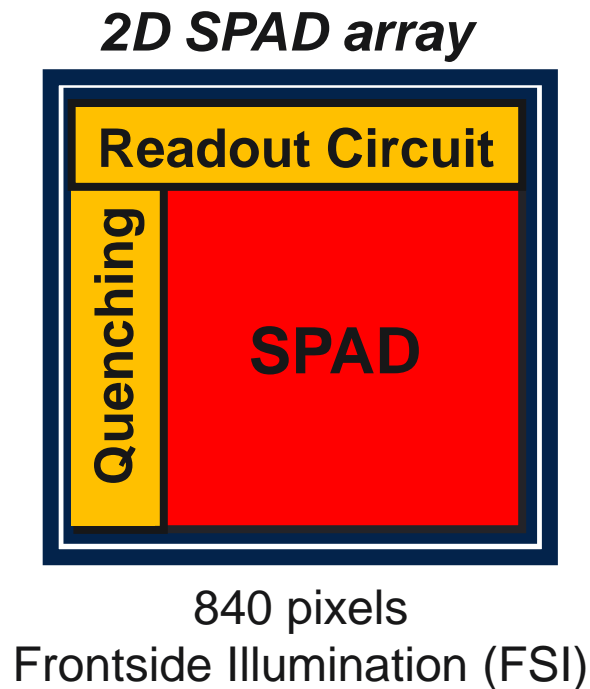
Motivations

- Study of Total Ionizing Dose (TID) effects with X-rays and γ -rays for two SPAD technologies up to 320 krad(SiO_2) (SPADs unbiased)



Motivations

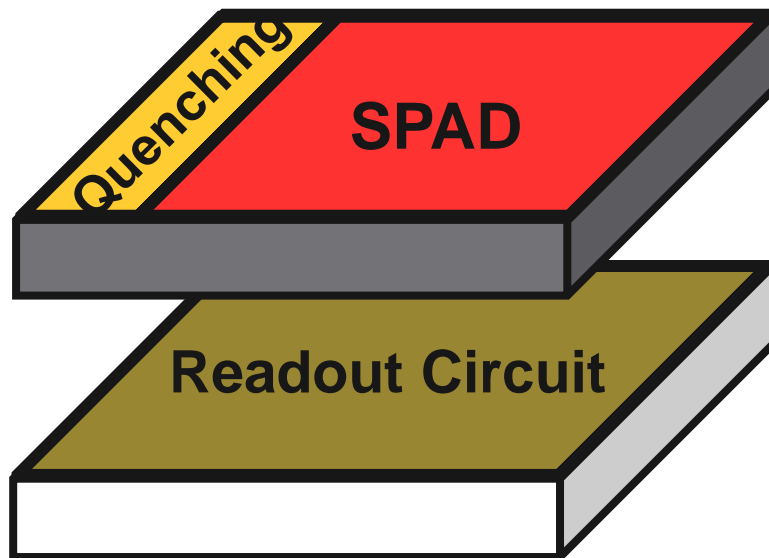
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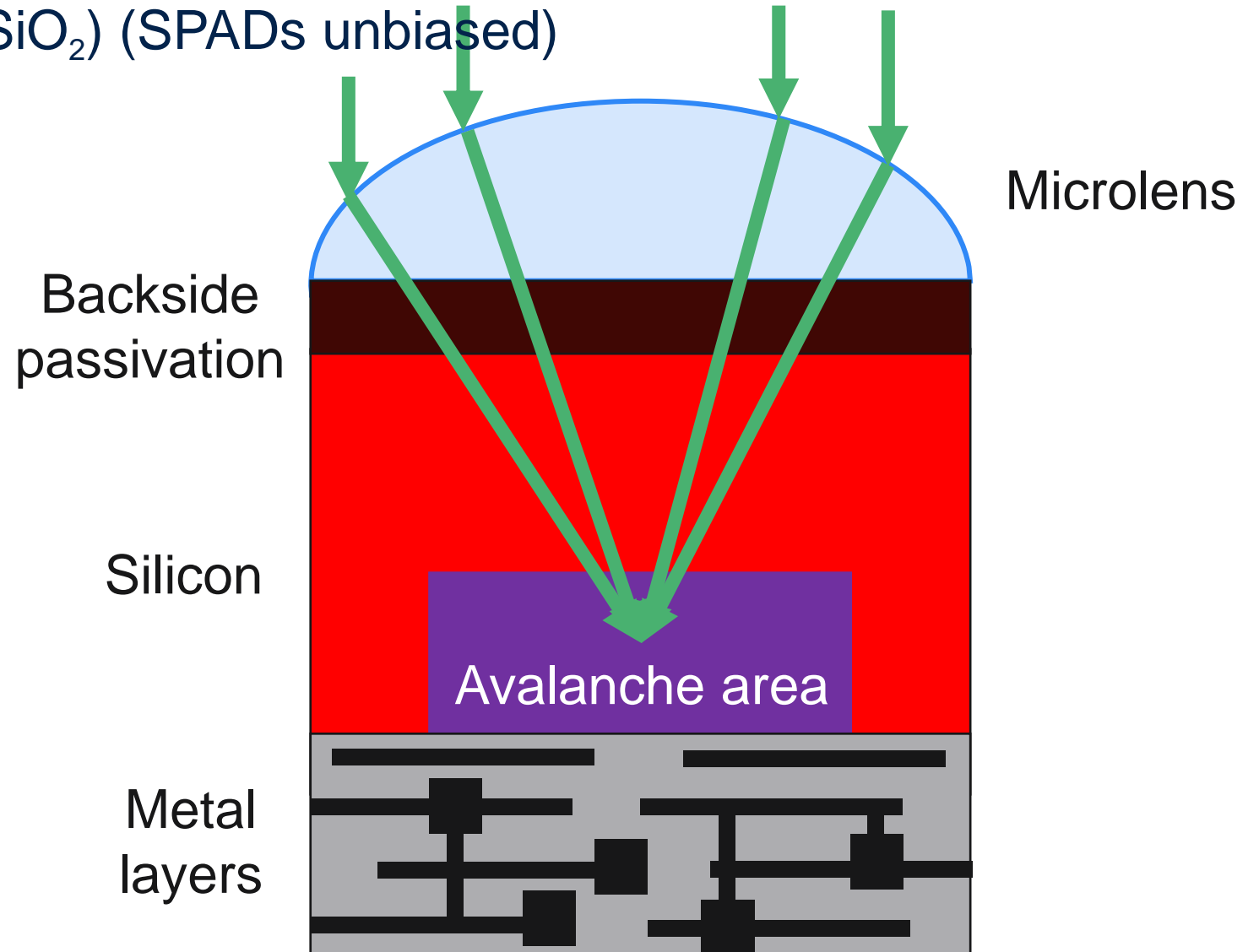
Motivations

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3D SPAD array



1024 pixels
Backside illumination (BSI)

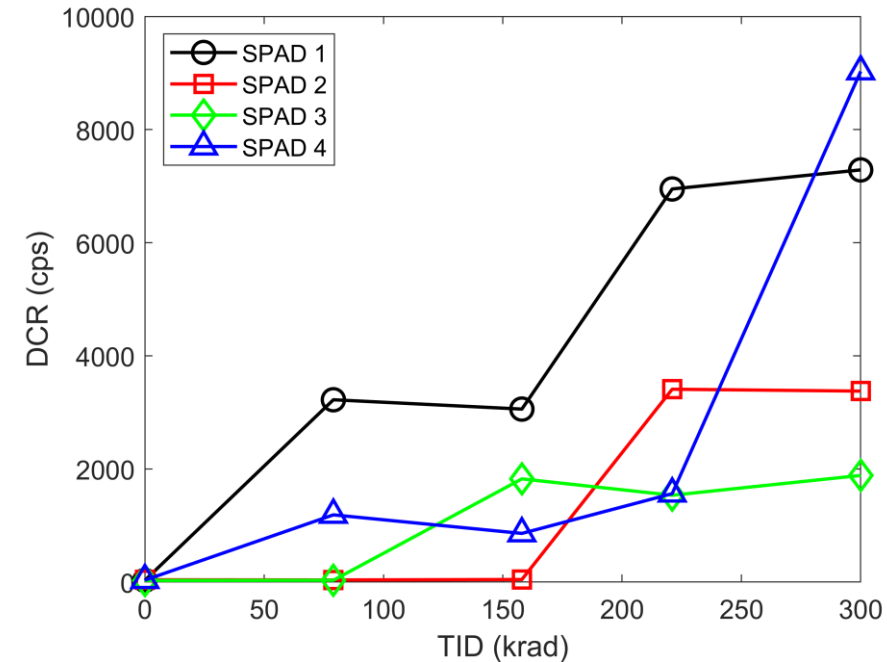
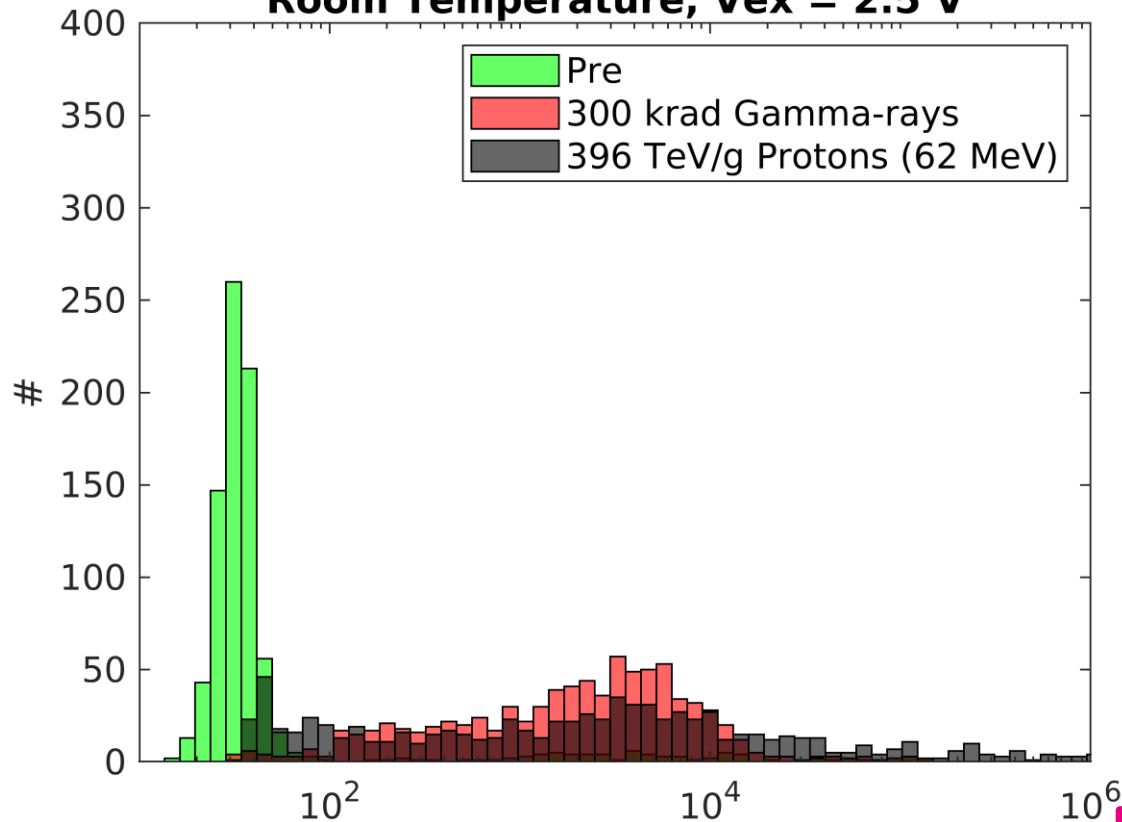


γ -rays on 2D-SPAD arrays: DCR distributions

γ -ray irradiation

- For approx. the same TID, different degradation
- Large spread of DCR distribution = signature of **displacement damages induced by γ -rays**

Room Temperature, Vex = 2.5 V

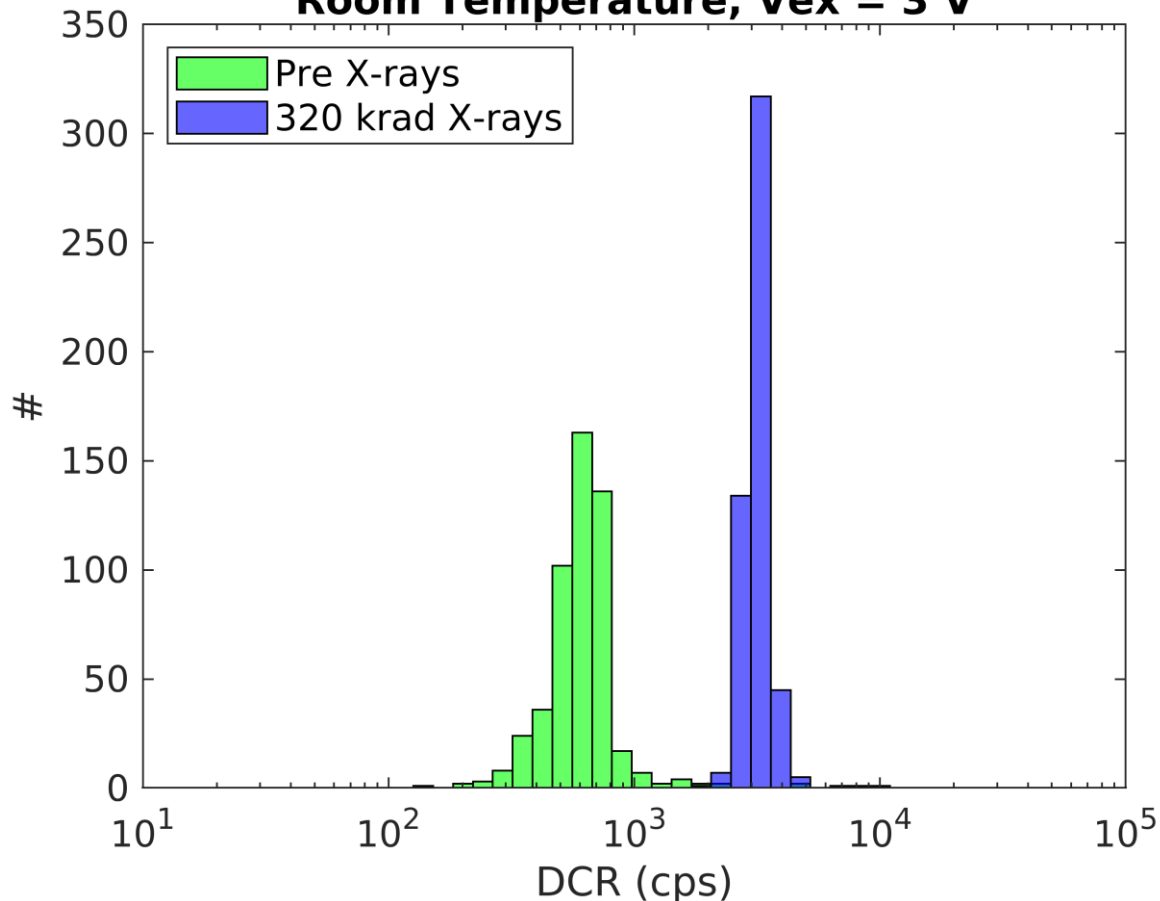


In 2D-SPADs: only the DDD contribution is seen after γ -rays → mainly Point Defects

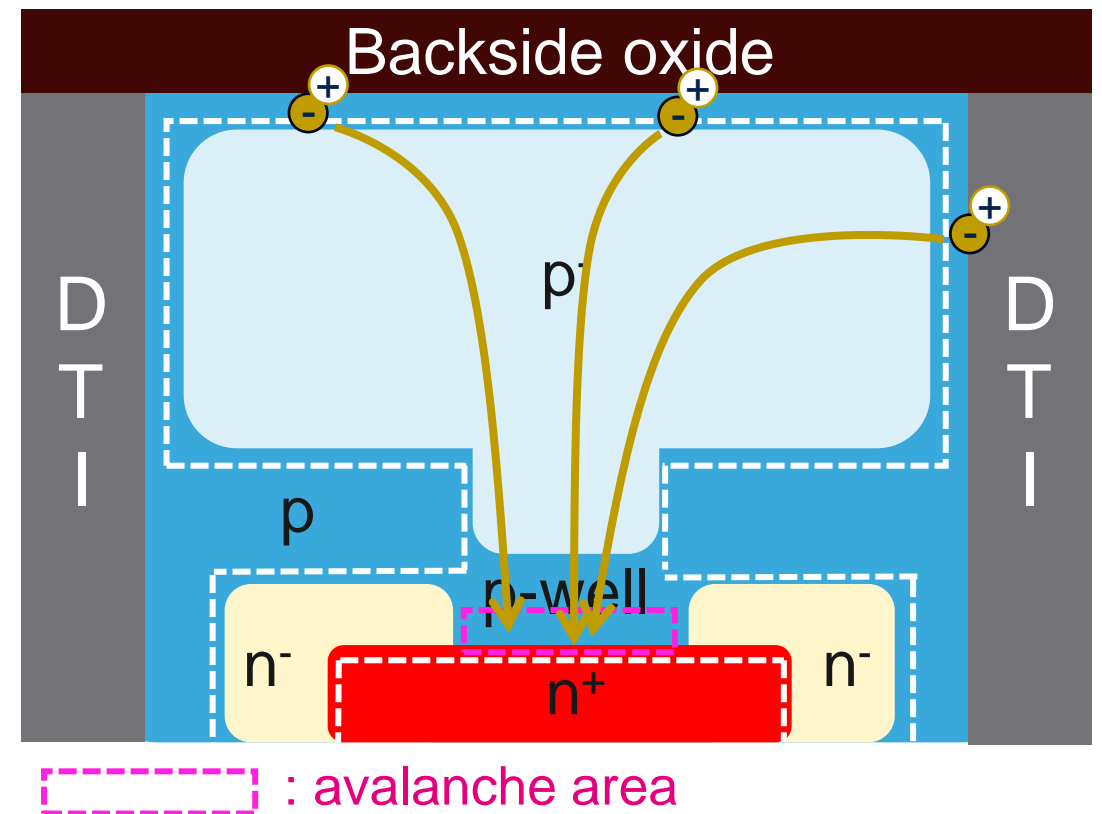
X-rays on 3D-SPAD arrays: DCR distributions

X-ray irradiation

Room Temperature, $V_{ex} = 3\text{ V}$



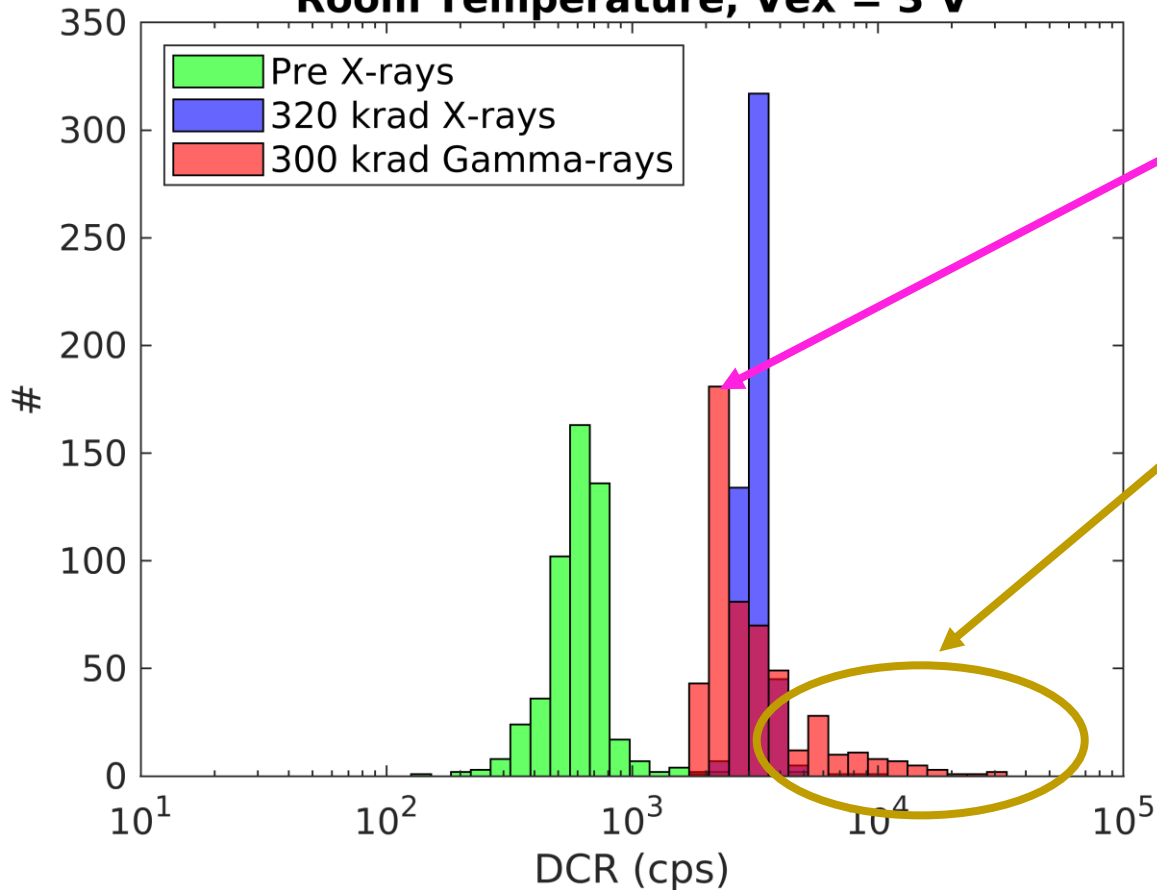
- Significant DCR increase after X-rays ($> 1000\text{ cps}$)
 - more Si/SiO₂ interfaces due to DTIs + backside oxides
 - electric field engineering: an electron entering the depleted volume drifts toward the avalanche area



γ -rays on 3D-SPAD arrays: DCR distributions

γ -ray irradiation

Room Temperature, Vex = 3 V



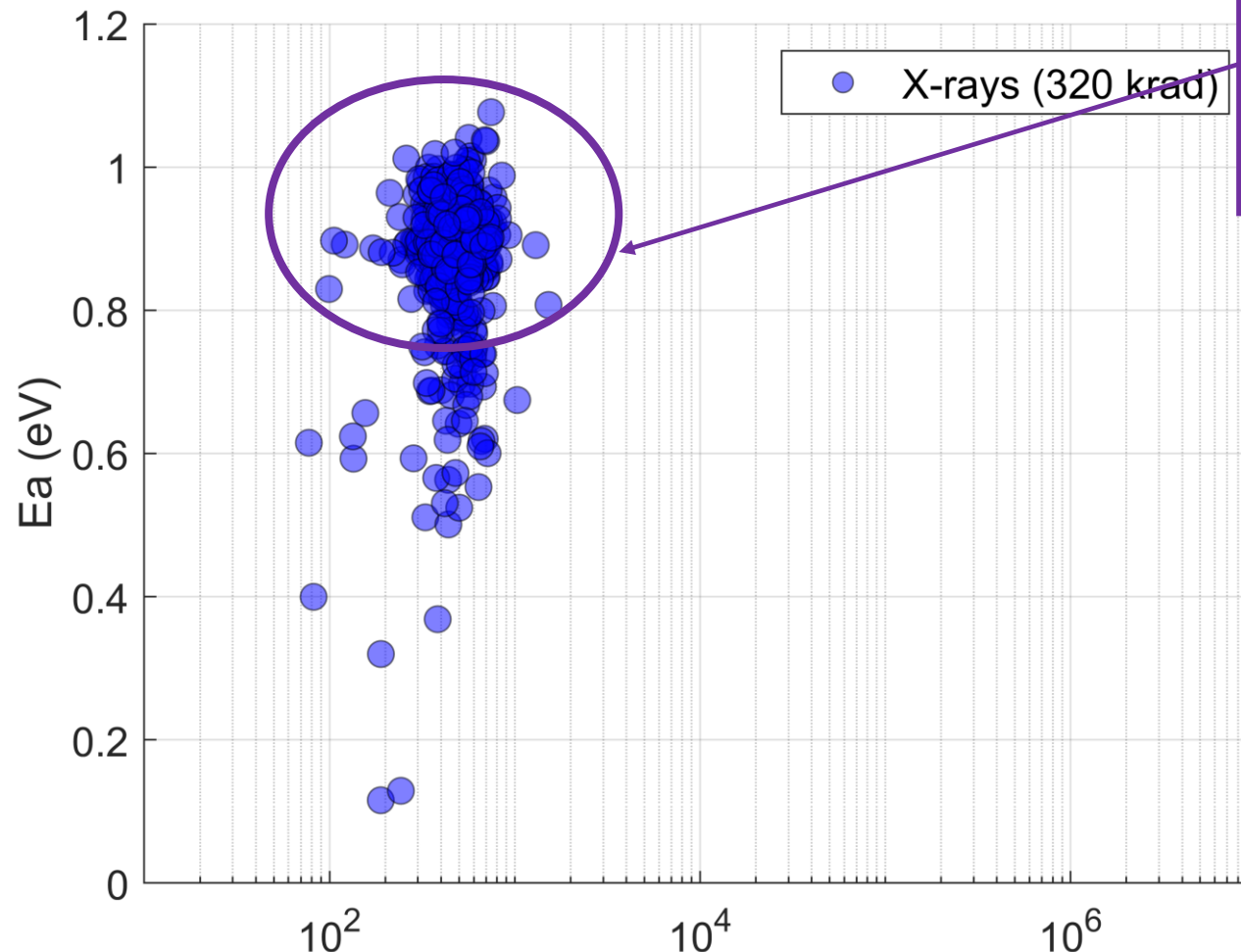
- Peaks due to **TID contribution**
→ **3D-SPADs impacted by ionizing effects**
- Again, spread toward high DCR not present with X-rays:
→ **Displacement damage contribution**

In 3D-SPADs: TID + DDD contributions are observed after γ -rays

$$DCR(T) \propto \exp\left(-\frac{E_a}{k_B \cdot T}\right)$$

Activation energies for 3D-SPAD arrays

- E_a extracted btw $-5\text{ }^{\circ}\text{C}$ and $22\text{ }^{\circ}\text{C}$



High E_a (near Si bandgap)

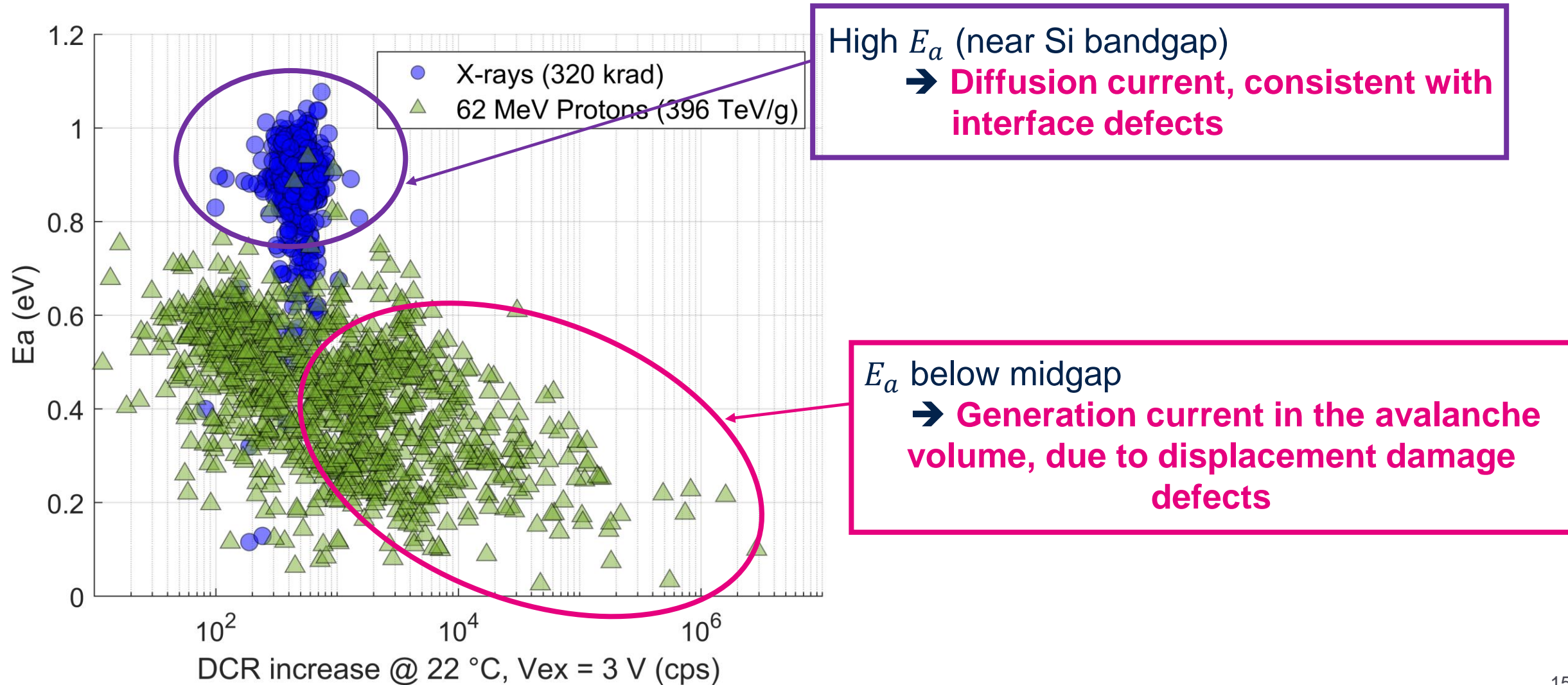
➔ **Diffusion current, consistent with interface defects**

DCR increase @ 22 °C, Vex = 3 V (cps)

$$DCR(T) \propto \exp\left(-\frac{E_a}{k_B \cdot T}\right)$$

Activation energies for 3D-SPAD arrays

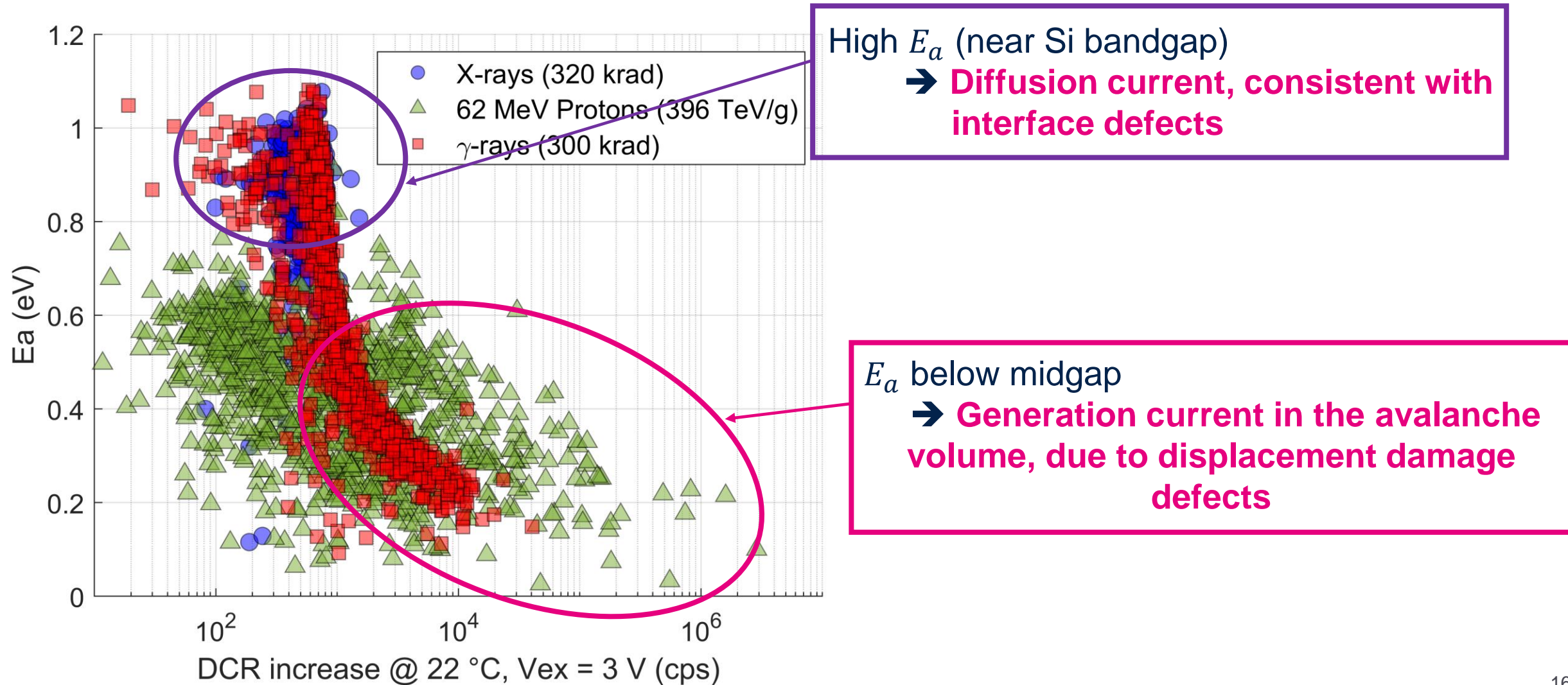
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Activation energies for 3D-SPAD arrays

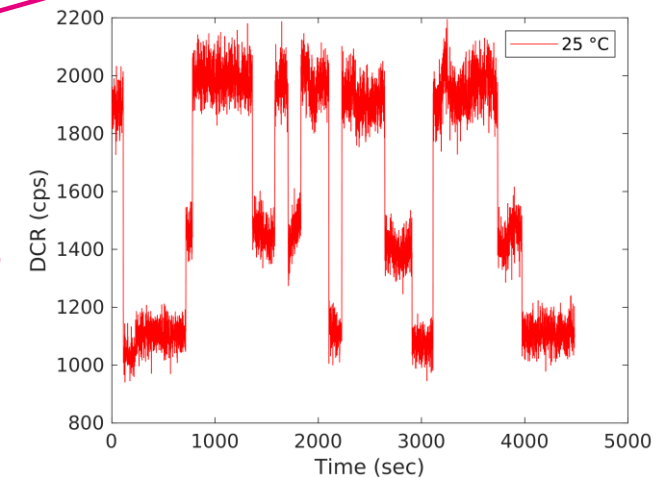
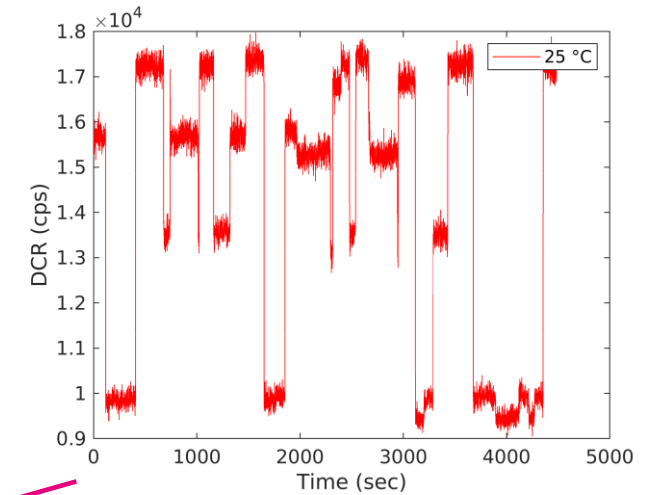
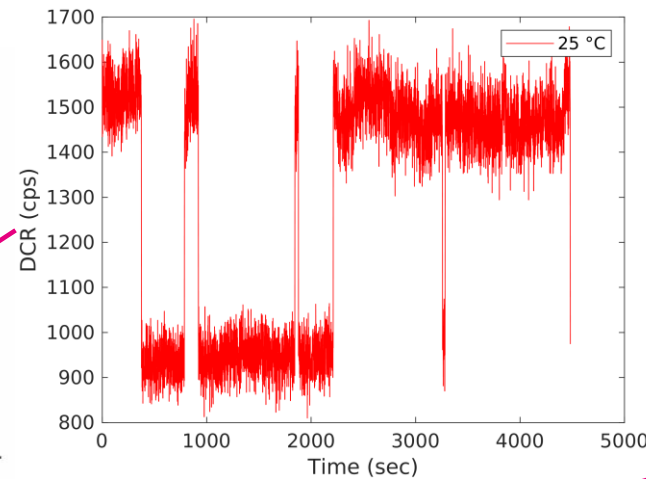
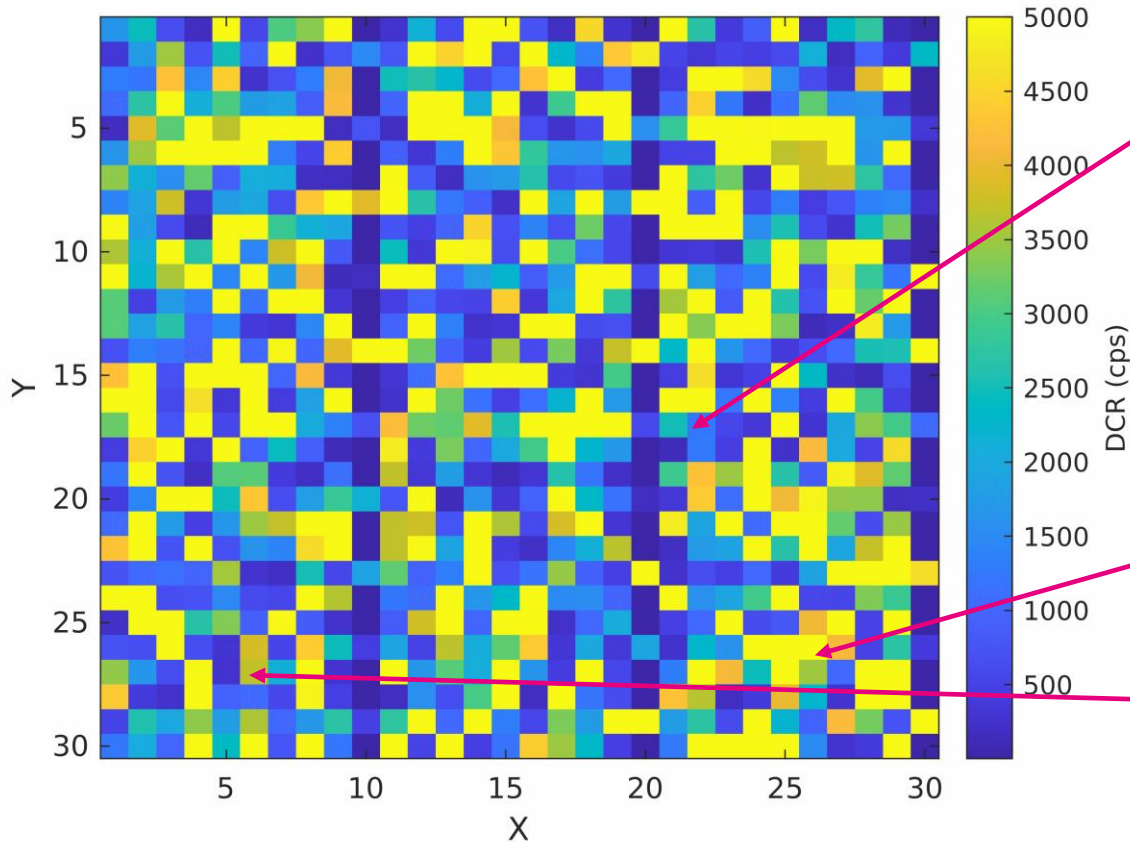
- E_a extracted btw **-5 °C** and **22 °C**



Induced Random Telegraph Signal (RTS)

- RTS = variation with time of a signal (here the DCR) over two or more discrete levels due to meta-stable defects

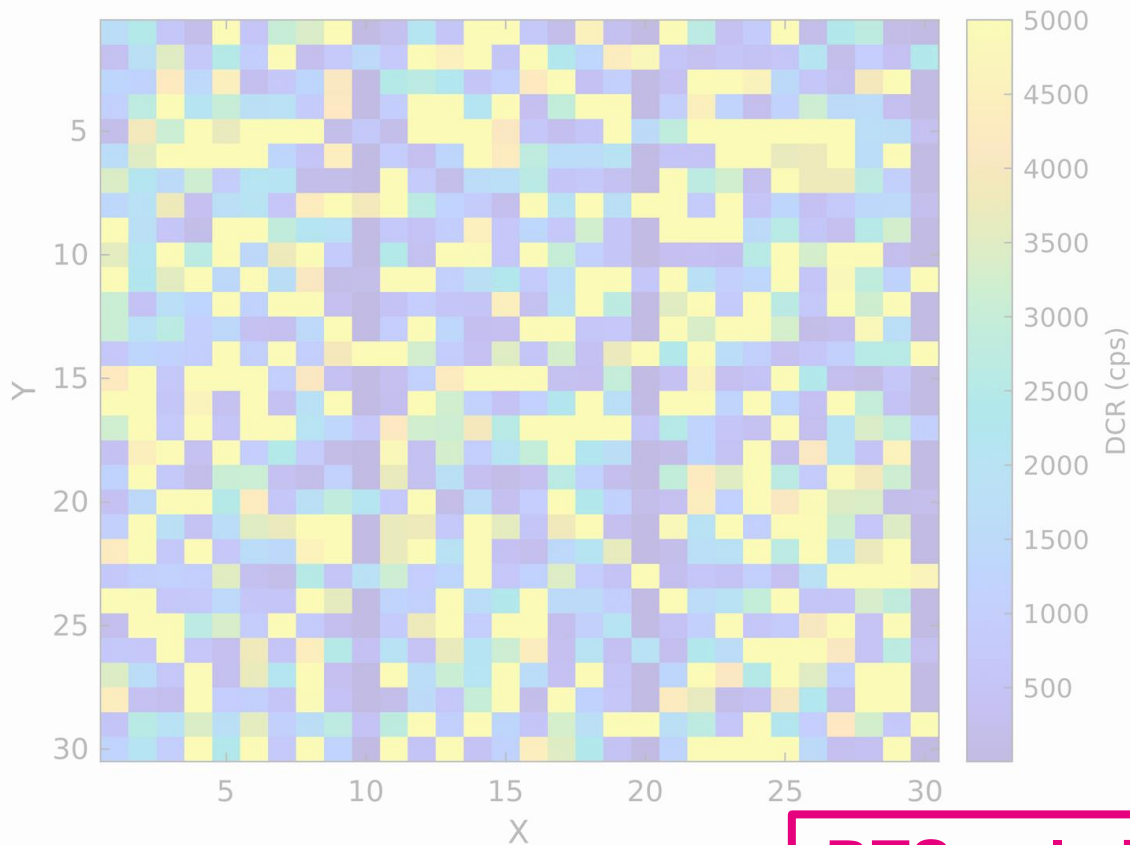
2D-SPAD array after γ -rays



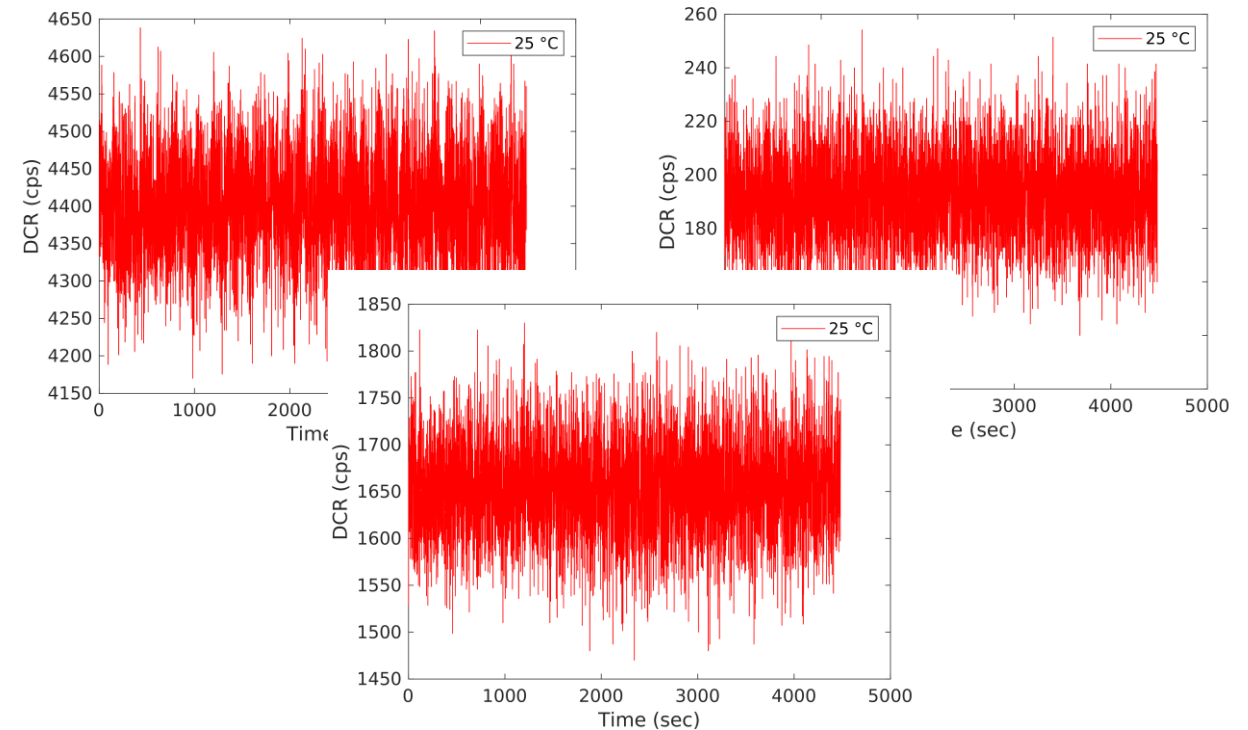
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2D-SPAD array after γ -rays



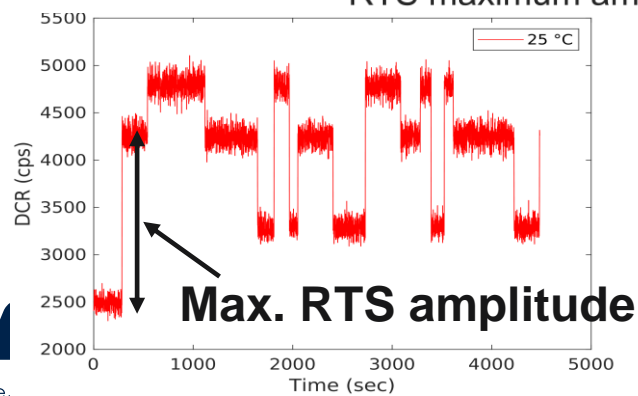
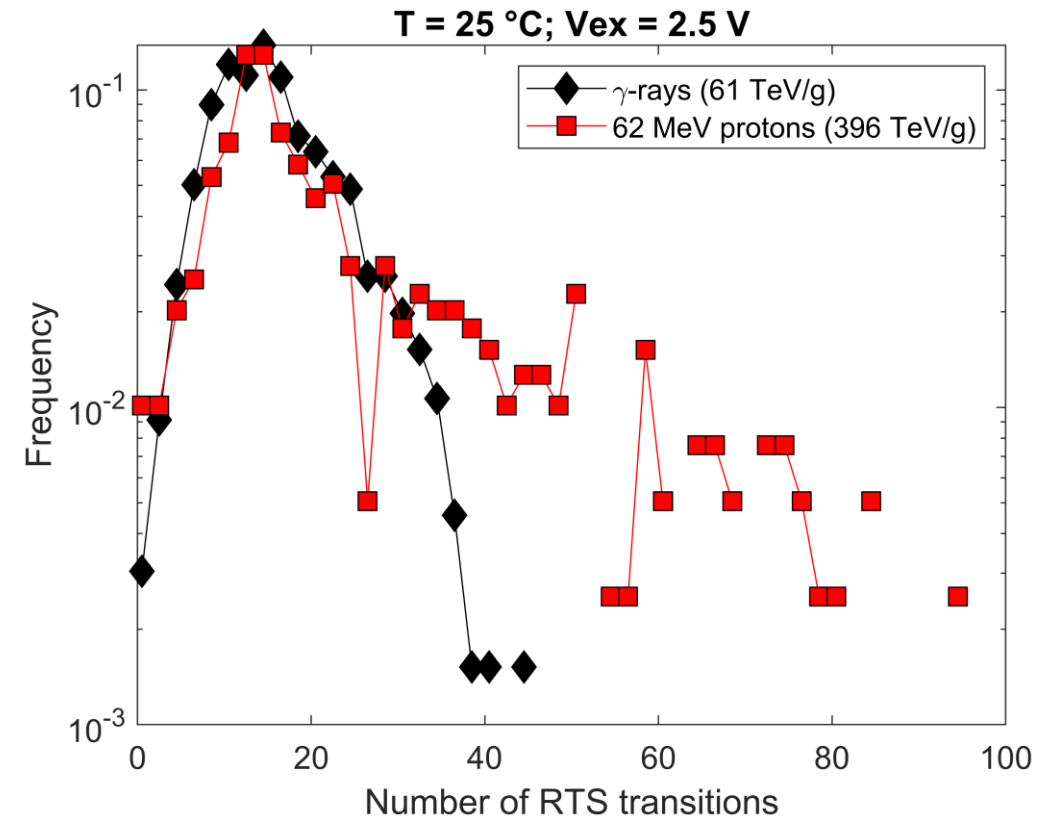
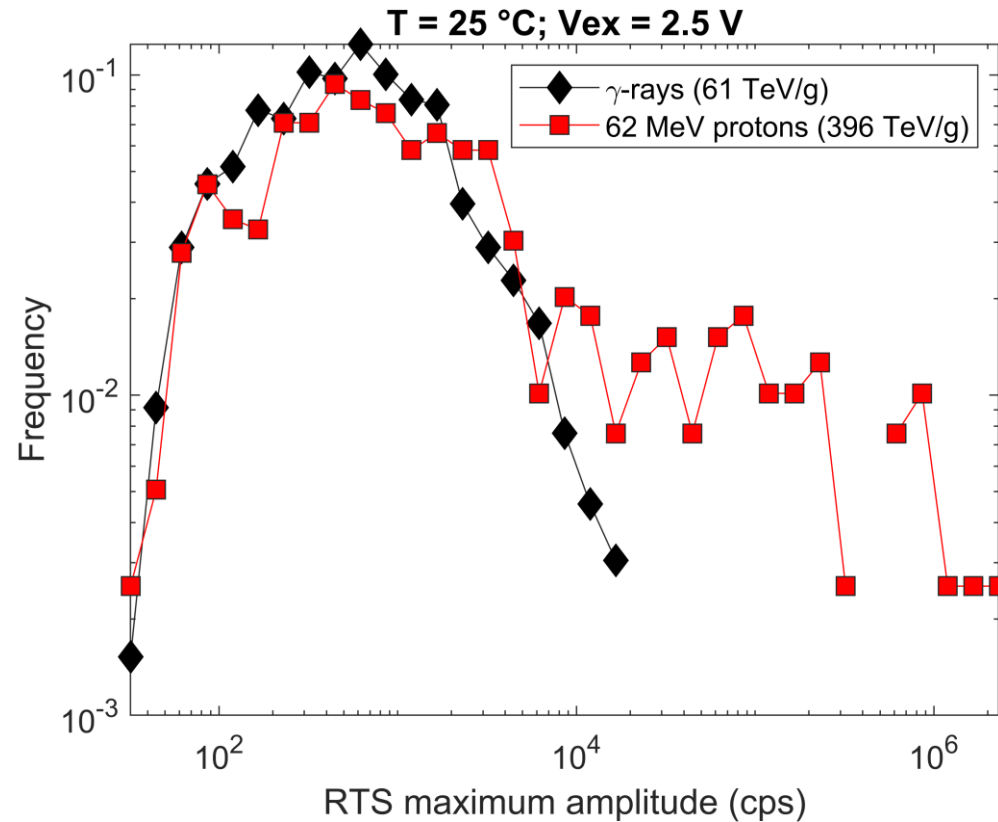
2D-SPAD + 3D-SPAD arrays after X-rays



No TID-induced RTS visible

RTS only induced by displacement damages in silicon after γ -rays ... so by point defects ?!

RTS induced by γ -rays and protons on 2D-SPADs



Consistent with two RTS origins: Point Defects + Clusters

Conclusion

- X-ray and γ -ray irradiation were performed on 2D- and 3D-SPAD technology up to 320 krad(SiO_2)
- 2D-SPADs slightly degraded after X-rays **due to interface traps generating charges that are swept out before reaching the avalanche volume**
- 3D-SPADs impacted by TID effects due to both **DTI + backside oxides + designed electric field**
- Measurable contribution of **the displacement damage contribution of γ -ray** in 2D- and 3D-SPADs
 - Confirmation with activation energy comparisons with proton irradiation data
- RTS SPADs **seen after γ -ray irradiation but not after x-rays**
 - **Point defects can be another origin of RTS** (with defect clusters)

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